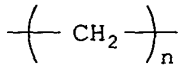
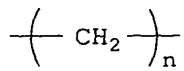
3. (Amended) The laminate according to claim 1, wherein not less than 50% in terms of molar fraction of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3):



(3)

wherein n is an integer of 1 to 15.

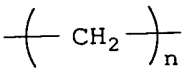
4. (Amended) The laminate according to claim 1, wherein 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3):



(3)

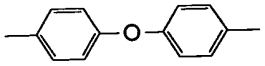
wherein n is an integer of 1 to 15.

5. (Amended) The laminate according to claim 1, wherein 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 30% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):



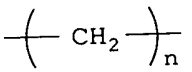
(3)

wherein n is an integer of 1 to 15; and



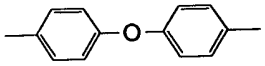
(4)

6. (Amended) The laminate according to claim 1, wherein 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):



(3)

wherein n is an integer of 1 to 15; and



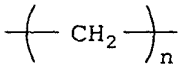
(4)

7. (Amended) The laminate according to claim 1, wherein at least one of the resin layers constituting the insulating layer is formed of a low expansion resin having a coefficient of expansion of 0 to 40 ppm.

8. (Amended) The laminate according to claim 1, wherein all the resin layers constituting the insulating layer are formed of the polyimide resin.

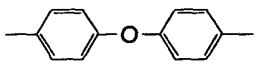
9. (Amended) The laminate according to claim 1, wherein the insulating layer, which forms an interface with at least one of the inorganic material layers, is formed of a polyimide resin,

said polyimide resin being such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):



(3)

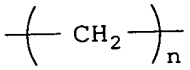
wherein n is an integer of 1 to 15; and



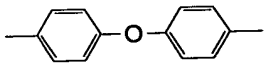
(4)

10. (Amended) The laminate according to claim 1, wherein said insulating layer has a laminate structure of first insulating layer/second insulating layer/third insulating layer, the first insulating layer and the third insulating layer are formed of a polyimide resin such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4), and

the second insulating layer is formed of a low expansion resin having a coefficient of expansion of 0 to 40 ppm:


(3)

wherein n is an integer of 1 to 15; and


(4)

11. (Amended) The laminate according to claim 1, wherein the inorganic material layers are such that both the inorganic material layers are formed of copper alloy, both the inorganic material layers are formed of copper, one of the inorganic material layers is formed of copper with the other inorganic material layer being formed of copper alloy, or one of the

inorganic material layers is formed of copper or copper alloy with the other inorganic material layer is formed of stainless steel.

12. (Amended) An electronic circuit component produced by etching the laminate according to claim 1.

13. (Amended) A suspension for a hard disk drive, produced by etching the laminate according to claim 1.

14. (Amended) An electronic circuit component produced by removing the insulating layer in the laminate according to claim 1 by a wet process to form a desired shape.

15. (Amended) A suspension for a hard disk drive, produced by removing the insulating layer in the laminate according to claim 1 by a wet process to form a desired shape.

16. (Amended) An electronic circuit component produced by removing the insulating layer in the laminate according to claim 1 with a basic solution to form a desired shape.

17. (Amended) A suspension for a hard disk drive, produced by removing the insulating layer in the laminate according to claim 1 with a basic solution to form a desired shape.

18. (Amended) An electronic circuit component produced by removing the insulating layer in the laminate according to claim 1 with an alkali-amine solution to form a desired shape.

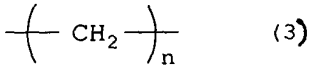
19. (Amended) A suspension for a hard disk drive, produced by removing the insulating layer in the laminate according to claim 1 with an alkali-amine solution to form a desired shape.

20. (Amended) An electronic circuit component produced by removing the insulating layer in the laminate according to claim 1 by a wet process to form a desired shape, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal of the insulating layer.

21. (Amended) A suspension for a hard disk drive, produced by removing the insulating layer in the laminate according to claim 1 by a wet process to form a desired shape, an inorganic nitride layer and/or an inorganic fluoride layer being absent on

the surface of the inorganic material layer exposed by the removal of the insulating layer.

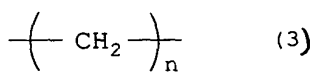
24. (Amended) The insulating film according to claim 22, wherein the polyimide resin is an adhesive polyimide having a structure such that not less than 50% in terms of molar fraction of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3):



(3)

wherein n is an integer of 1 to 15.

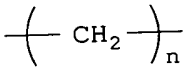
25. (Amended) The insulating film according to claim 22, wherein the polyimide resin is an adhesive polyimide having a structure such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3):



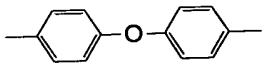
(3)

wherein n is an integer of 1 to 15.

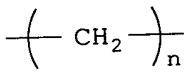
26. (Amended) The insulating film according to claim 22, wherein the polyimide resin is an adhesive polyimide having a structure such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 30% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):


(3)

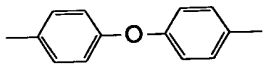
wherein n is an integer of 1 to 15; and


(4)

27. (Amended) The insulating film according to claim 22, wherein the polyimide resin is an adhesive polyimide having a structure such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):


(3)

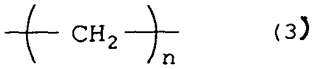
wherein n is an integer of 1 to 15; and


(4)

28. (Amended) The insulating film according to claim 22, wherein at least one of the resin layers constituting the insulating layer is formed of a polyimide resin having a coefficient of expansion of 0 to 40 ppm.

29. (Amended) The insulating film according to claim 22, wherein all the resin layers constituting the insulating layer are formed of the polyimide resin.

30. (Amended) The insulating film according to claim 22, wherein, in each of front surface and backside surface insulating layers, the polyimide resin is an adhesive polyimide resin such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3):



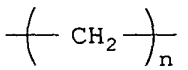
(3)

wherein n is an integer of 1 to 15.

31. (Amended) The insulating film according to claim 22, wherein

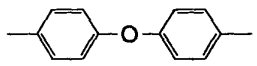
said insulating layer has a laminate structure of a first insulating layer and a second insulating layer,

the first insulating layer and the second insulating layer are formed of a polyimide resin such that 100% of the divalent organic group contained in R_1 in formula (1) or (2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4):



(3)

wherein n is an integer of 1 to 15; and



(4)

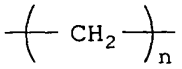
32. (Amended) The insulating film according to claim 22, wherein

said insulating layer has a laminate structure of first insulating layer/second insulating layer/third insulating layer,

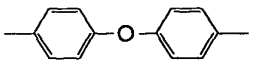
the first insulating layer and the third insulating layer are formed of a polyimide resin having a structure such that 100% of the divalent organic group contained in R_1 in formula (1) or

(2) is accounted for by a divalent organic group represented by formula (3) and not less than 80% in terms of molar fraction of the divalent organic group contained in R_2 is accounted for by a divalent organic group represented by formula (4), and

the second insulating layer is formed of a low expansion polyimide resin having a coefficient of expansion of 0 to 40 ppm:


(3)

wherein n is an integer of 1 to 15; and


(4)

33. (Amended) A laminate comprising an inorganic material layer and, stacked on the inorganic material layer, the insulating film according to claim 22.

34. (Amended) An electronic circuit component produced by etching the insulating film according to claim 22.

35. (Amended) A suspension for a hard disk drive, produced by etching the insulating film according to claim 22.

36. (Amended) An electronic circuit component produced by removing the insulating film according to claim 22 by a wet process to form a desired shape.

37. (Amended) A suspension for a hard disk drive, produced by removing the insulating film according to claim 22 by a wet process to form a desired shape.

38. (Amended) An electronic circuit component produced by removing the insulating film according to claim 22 with a basic solution to form a desired shape.

39. (Amended) A suspension for a hard disk drive, produced by removing the insulating film according to claim 22 with a basic solution to form a desired shape.

40. (Amended) An electronic circuit component produced by removing the insulating film according to claim 22 with an alkali-amine solution to form a desired shape.

41. (Amended) A suspension for a hard disk drive, produced by removing the insulating film according to claim 22 with an alkali-amine solution to form a desired shape.

44. (Amended) The laminate according to claim 42, wherein the insulating layer comprises a core insulating layer and an adhesive layer provided on both sides of the core insulating layer.

47. (Amended) The laminate according to claim 42, wherein at least one of the layers constituting the insulating layer is formed of a polyimide resin.

48. (Amended) The laminate according to claim 42, wherein all the layers constituting the insulating layer are formed of a polyimide resin.

49. (Amended) The laminate according to claim 42, wherein the etching rate ratio in the insulating layer is a value as measured in etching with an alkali solution.

50. (Amended) The laminate according to claim 42, wherein the inorganic material constituting the laminate is selected from copper, alloy copper, and stainless steel.

51. (Amended) An electronic circuit component produced by etching the laminate according to claim 42.

52. (Amended) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process.

53. (Amended) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

54. (Amended) A suspension for a hard disk drive, produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.